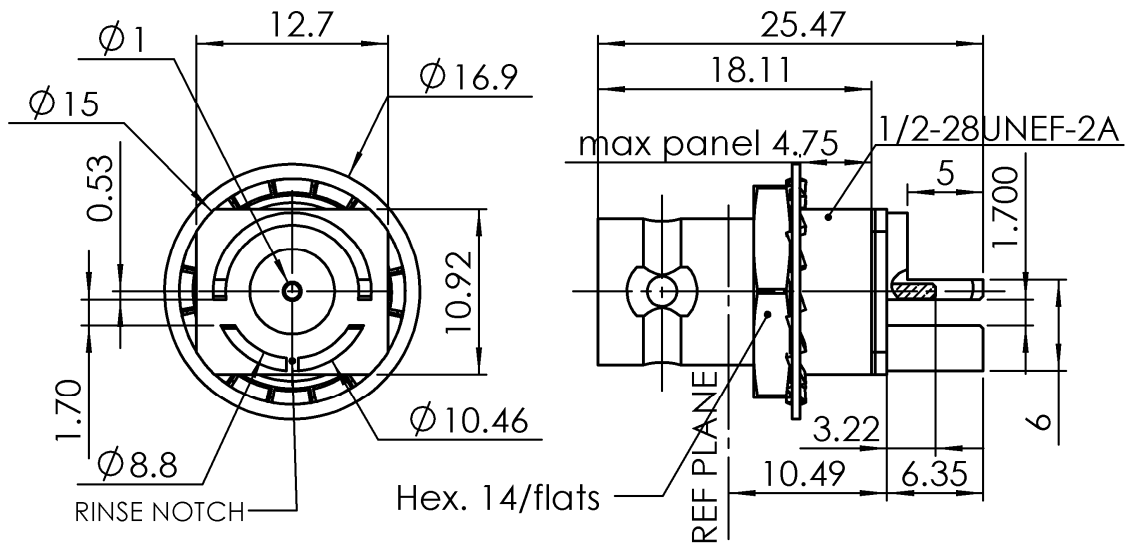


STRAIGHT BULKHEAD JACK, PCB

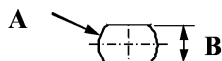
R142.567.703

EDGE MOUNT

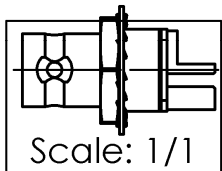
Series : **BNC 75 HDTV**



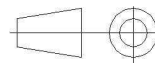
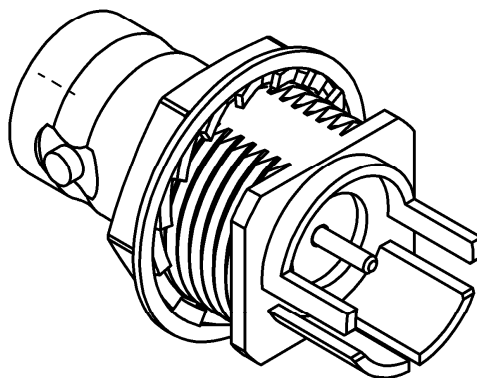
PANEL CUT OUT



mm		
	Maxi	mini
A	12.95	12.83
B	11.35	11.25



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY	BRASS	NPGR
CENTER CONTACT	BERYLLIUM COPPER	NPGR
OUTER CONTACT		
INSULATOR	PTFE	
GASKET		
OTHERS PARTS	BRASS	NICKEL2
-	-	-
-	-	-

Issue : 0941 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



STRAIGHT BULKHEAD JACK, PCB

R142.567.703

EDGE MOUNT

Series : **BNC 75 HDTV**

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance	75	Ω
Frequency	0-6	GHz
VSWR	1.04 + 0.0200	x F(GHz) Maxi
Insertion loss	0.1	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (55*	- F(GHz)) dB Maxi
Voltage rating	500	Veff Maxi
Dielectric withstanding voltage	1500	Veff mini
Insulation resistance	5000	M Ω mini

Operating temperature	-65/+165	$^{\circ}$ C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction

Others :

*From 2 to 3GHz

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	18	N mini
Axial force – Opposite end	18	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	370	N.cm
Mating life	1000	Cycles mini
Weight	11.0800	g

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STRAIGHT BULKHEAD JACK, PCB

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EDGE MOUNT

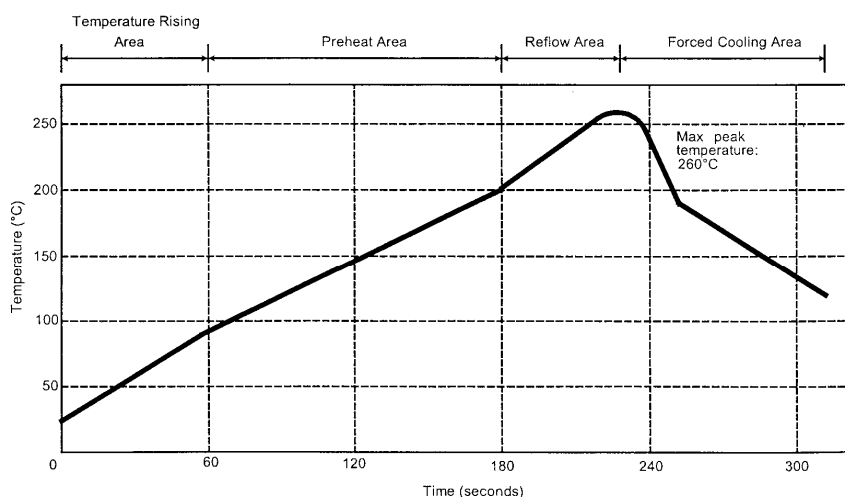
Series : BNC 75 HDTV

SOLDER PROCEDURE

1. Deposit solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .
5. Verification of solder joints and position of the component by visual inspection.

NOTE : The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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